

Amendments to the Claims:

Please cancel claims 7-15 and amend claims 1, 2 and 6, as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently Amended). A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted ~~or a conductive material laminated plate for manufacturing said printed circuit board,~~

5 said jig comprising:

a plate which has a weak-adherence adhesive pattern on a surface of the plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface of the printed circuit board,
10 and said printed circuit board ~~or said conductive material laminated plate~~ is placed and held on the surface of said plate, and

said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.

Claim 2 (Currently Amended). A holding and conveyance jig for detachably holding and conveying a printed circuit board on

which electronic components are mounted or a conductive material
~~laminated plate for manufacturing said printed circuit board,~~
5 said jig comprising:

a plate which has a weak-adherence adhesive layer on a
surface of the plate; wherein:

said printed circuit board has a conductive portion and a
non-conductive portion on a surface of the printed circuit board,
10 and said printed circuit board or ~~said conductive material~~
~~laminated plate~~ is placed and held on the surface of said plate,
and

a weak-adherence adhesive pattern subjected to surface
roughening is formed on a surface of said weak-adherence adhesive
15 layer at a position corresponding to said conductive portion.

Claim 3 (Previously Presented). The holding and conveyance
jig according to claim 1, wherein said weak-adherence adhesive
pattern has a plurality of thickness regions differing in
thickness from the surface of said plate.

Claim 4 (Previously Presented). The holding and conveyance
jig according to claim 1, wherein said weak-adherence adhesive
pattern has a plurality of adhesive strength regions differing in
adhesive strength.

Claim 5 (Previously Presented). The holding and conveyance jig according to claim 2, wherein a non-adhesive pattern is formed at a position corresponding to said conductive portion on the surface of said weak-adherence adhesive layer.

Claim 6 (Currently Amended). A method of conveying a printed circuit board ~~on which comprising the steps of:~~
~~providing on said printed circuit board electronic components which are mounted thereon, said printed circuit board~~
5 ~~having on a surface thereof and which has~~ a conductive portion and a non-conductive portion ~~on a surface of the printed circuit board, and~~

10 ~~conveying said printed circuit board while detachably holding said printed circuit board on a surface of a holding and conveyance jig in which a weak-adherence adhesive pattern is provided on [[a]] the surface of the jig, the method comprising the step of:~~

15 ~~holding said printed circuit board on the surface of said holding and conveyance jig in a manner such that said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.~~

Claims 7-15 (Cancelled).

Claim 16 (Previously Presented). The holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from the surface of said plate.

Claim 17 (Previously Presented). The holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 18 (Previously Presented). The holding and conveyance jig according to claim 3, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 19 (Previously Presented). The holding and conveyance jig according to claim 16, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.